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Attorney's Docket No. S1022/8246

Date Mailed: May 11, 2001

7. (Amended) The electronic circuit of claim 1, wherein the surface of the base which does not receive the double faced adhesive is provided to receive the printing of a pattern, of a text or of a code.

8. (Amended) A method of manufacturing the circuit of claim 1, wherein the attachment of the double faced adhesive on the base includes the steps of:

forming a rectangle of double faced adhesive including a slot,  
gluing the adhesive rectangle on a packaging protective film,  
ungluing the adhesive rectangle from the protective film, and assembling it on the base.

REMARKS

This is a preliminary amendment in which the claims have been amended to place them in better form before initial examination by the Examiner. Favorable action is hereby earnestly solicited.

Respectfully submitted,

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AMENDED CLAIMS SHOWING THE AMENDMENTS

1. (Amended) An electronic circuit including a planar base [(14)], an antenna [(16)] attached on a first surface of the base, and a chip [(12)] connected to the antenna, characterized in that a double faced adhesive [(20)] is glued on one of the base surfaces, a slot [(21)] being made in the double faced adhesive and the chip being arranged at least partially in this slot.

2. (Amended) The electronic circuit of claim 1, [characterized in that] wherein the chip is glued on the first surface of the base and is connected to the antenna by connection wires [(18)], the wires and the chip being covered with a drop of resin [(19, 22)].

3. (Amended) The electronic circuit of claim 1, [characterized in that] wherein the etched surface of the chip faces the first surface of the base, and the chip is connected to the antenna by welding beads [(26)].

4. (Amended) The electronic circuit of claim 1, [characterized in that] wherein the etched surface of the chip faces the back of the first surface of the base, the chip is placed in a slot [(21)] made through the base, and the chip is connected to the antenna by welding beads [(26)], the chip being attached to the base by a drop of resin [(22)].

5. (Amended) The electronic circuit of claim 1, [characterized in that] wherein the etched surface of the chip faces the back of the first surface of the base and the chip is connected to the antenna by welding beads [(26)] located in connection slots [(25)] going through the base [(14)], the chip being attached to the base by a drop of resin [(22)].

6. (Amended) The electronic circuit of [any of the preceding claims, characterized in that] claim 1, wherein the base [(14)] is made of a flexible sheet.

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7. (Amended) The electronic circuit of [any of the preceding claims, characterized in that] claim 1, wherein the surface of the base which does not receive the double faced adhesive is provided to receive the printing of a pattern, of a text or of a code [(38)].

8. (Amended) A method of manufacturing the circuit of claim 1, [characterized in that] wherein the attachment of the double faced adhesive on the base includes the steps of:

forming a rectangle of double faced adhesive [(20)] including a slot [(21)],

gluing the adhesive rectangle on a packaging protective film [(24)],

ungluing the adhesive rectangle from the protective film, and assembling it on the base [(14)].

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